




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-09-22
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
	Legal Declaration *
	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS1H100MF	7N6U*Z24P83V	A	ZA41	2017-09-22
	Amount	UoM	Unit type	ST ECOPACK Grade
	16.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOF	2.95,1.90,0.85	2	flat	
Comment	Package: DO-216AA-Flat			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	DIE	438
Lead	0.76	SOFT SOLDER	47750

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7N6U*Z24P83V					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.569	mg	supplier	die	Silicon (Si)	7440-21-3		0.548	mg	963095	34245
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	7030	250
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1757	63
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1757	63
				supplier	metallization	Nickel (Ni)	7440-02-0		0.003	mg	5272	188
				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	5272	188
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	7030	250
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1757	63
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.004	mg	7030	250
				Leadframe & Clip	Copper and its alloy	6.321	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.006	mg	949	375
supplier	alloy	Phosphorus (P)	12185-10-3						0.003	mg	475	188
Soft solder	Other organic material	0.826	mg	supplier	solder	Silver (Ag)	7440-22-4		0.020	mg	24214	1250
				supplier	solder	Tin (Sn)	7440-31-5		0.042	mg	50847	2625
				JIG-R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	0.764	mg	924939	47750
Encapsulation	Other organic material	8.141	mg	Supplier	mold compound	Silica , amorphous,fused	60676-86-0		6.514	mg	800147	407125
				Supplier	mold compound	Epoxy resin proprietare,resin unknown	29690-82-2		1.058	mg	129959	66125
				Supplier	mold compound	Benzophenone teracarboxylic anhydride	2421-28-5		0.081	mg	9950	5063
				Supplier	mold compound	Silica, quartz	14808-60-7		0.407	mg	49994	25438
				Supplier	mold compound	Carbon black	1333-86-4		0.081	mg	9950	5063
Finishing	Other inorganic material	0.143	mg	Supplier	connection coating	Tin (Sn)	7440-31-5		0.143	mg	1000000	8938